



FOR IMMEDIATE RELEASE

Huawei Technologies Joins HDP User Group International

Scottsdale, Ariz., June 15, 2008—The High Density Packaging User Group International, Inc. (HDP), a global non-profit cooperative research and development organization for the Electronics industry, announces that Huawei Technologies, Inc. has joined the organization as an Executive Member. Huawei will participate in HDP User Group’s technical programs, and will also have a seat on the Board of Directors.

The HDP organization and its member companies are excited about the addition of Huawei Technologies and look forward to sharing knowledge in current and future projects that will benefit all. “Huawei bring a wealth of knowledge and experience to HDP, and their support will be beneficial to all of our activities,” said Marshall Andrews, executive director of HDP.

About Huawei Technologies:

Huawei Technologies is a leader in providing next generation telecommunications networks for operators around the world. The company is committed to providing innovative and customized products, services and solutions to create long-term value and potential growth for its customers.

Huawei's products and solutions cover wireless products (HSPA/WCDMA/EDGE/GPRS/GSM, CDMA2000 1X EVDO/CDMA2000 1X, TD-SCDMA, WiMAX), core network products (IMS, Mobile Softswitch, NGN), network products (FTTX, xDSL, Optical, Routers, LAN Switch), application and software (IN, mobile data service, Boss), as well as terminals (UMTS/CDMA). Major products are based on Huawei’s self-designed ASIC chips and shared platforms to provide high-quality and cost-effective products and solutions with quick response.

Huawei’s products are deployed in over 100 countries, and serve 31 of the world’s top 50 operators, as well as over one billion users worldwide. For more information, please visit <http://www.huawei.com>

About the HDP User Group International Inc.

HDP User Group (www.hdpug.org) is a global research and development organization based in Scottsdale AZ, dedicated to “reducing the costs and risks for the Telecommunications and Computer industries when using advanced electronic packaging

and assembly”. This international industry led group organizes and conducts R&D programs to address the technical issues facing the industry, including design, printed circuit board manufacturing, electronics assembly, and environmental compliance. HDP maintains additional offices in Austin, Texas; Stockholm, Sweden; and Tokyo, Japan.

For more information, visit HDP User Group on the Internet at www.hdpug.org or contact Darryl Reiner at darrylr@hdpug.org, phone number +1 480-951-1963.

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